GooDisplay

10.85 inch
E-paper Display Series
GDEM1085Z51

GooDisplay®

Dalian Good Display Co., Ltd.

Product Specifications

Customer	**Standard**
Description	**10.85" E-PAPER DISPLAY**
Model Name	**GDEM1085Z51**
Date	**2024/01/09**
Revision	**1.0**

	Design Engineering		
	Approval	**Check**	**Design**
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CONTENTS

1. Over View.....5
2. Features.....5
3. Mechanical 6
4.Mechanical Drawing of EPD Module.....7
5. Input/output Pin Assignment.....8
6. Electrical Characteristics.....9
6.1 Absolute Maximum Rating.....9
6.2 Panel DC Characteristics.....10
6.3 Panel AC Characteristics.....11
6.3.1 MCU Interface Selection.....11
6.3.2 MCU Serial Interface (4-wire SPI).....11
6.3.3 MCU Serial Interface (3-wire SPI).....12
6.3.4 Interface Timing.....12
7.Command Table.....14
8. Block Diagram.....34
9. Typical Application Circuit with SPI Interface.....35
10. Typical Operating Sequence.....36
10.1 OTP Operation Flow.....36
10.2 OTP Operation Reference Program Code.....37
11. Reliability Test.....38
12. Quality Assurance.....39
12.1 Environment.....39
12.2 Illuminance.....39
12.3 Inspect method.....39

12.4 Display area.....39
12.5 Ghosting test method.....39
12.6 Inspection standard.....40
12.6.1 Electric inspection standard.....40
12.6.2 Appearance inspection standard.....41
13.Packaging.....43
14. Others.....44

1. Over View

The display is a 10.85-inch TFT active matrix electrophoretic display, featuring a well-designed interface and reference system. It boasts a resolution of 1360×480 pixels, offering 1-bit grayscale with full display capabilities in black, white and red. Each panel is equipped with an integrated circuit that includes a gate buffer, source buffer, interface, timing control logic, oscillator, DC-DC converter, SRAM, look-up table (LUT), VCOM support, and border features.

2. Features

- 1360×480 pixels display
- High contrast
- High reflectance
- Ultra wide viewing angle
- Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Commercial temperature range
- Landscape, portrait modes
- Hard-coat antiglare display surface
- Ultra Low current deep sleep mode
- On chip display RAM
- Waveform can stored in On-chip OTP or written by MCU
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I^2C signal master interface to read external temperature sensor
- Built-in temperature sensor

3. Mechanical and Optical Specification

Parameter	Specifications	Unit	Remark
Screen Size	10.85	Inch	
Display Resolution	1360(H)×480(V)	Pixel	DPI:133
Active Area	259.76×91.68	mm	
Pixel Pitch	0.191×0.191	mm	
Pixel Configuration	Rectangle		
Outline Dimension	270.56(H)×105.92 (V) ×1.20(D)	mm	
Weight	66.8±0.5	g	

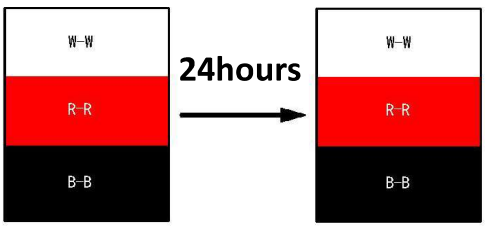
Symbol	Parameter	Conditions	Min	Typ.	Max	Units	Notes
KS	Black State L* value		-	13	15		3-1
	Black State A* value		-	4	6		3-1
	Black Ghosting ΔE		-	2	-		3-1
	After 24hour colour changed		-	2	-		3-4
WS	White State L* value		62	65	-		3-1
	White State A* value		-	0	1		3-1
	White Ghosting ΔE		-	2	-		3-1
	After 24hour colour changed		-	2	-		3-4
RS	Red State L* value		27	28	32		3-1
	Red State A* value		36	40	45		3-1
	Red Ghosting ΔE		-	3	-		3-1
	After 24hour colour changed		-	2	-		3-4
T update	Image update time	at 23 °C	-	20	-	sec	
R	White Reflectivity	White	30	34	-	%	3-1
CR	Contrast Ratio	Indoor	15:1	20	-		3-1 3-2
GN	2Grey Level	-	-	-	-		
Life		Temp:23±2°C Humidity:55±10%RH		5 years			3-3

Notes: 3-1. Luminance meter: Eye-One Pro Spectrophotometer.

3-2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.

3-3. When the product is stored. The display screen should be kept white and face up.

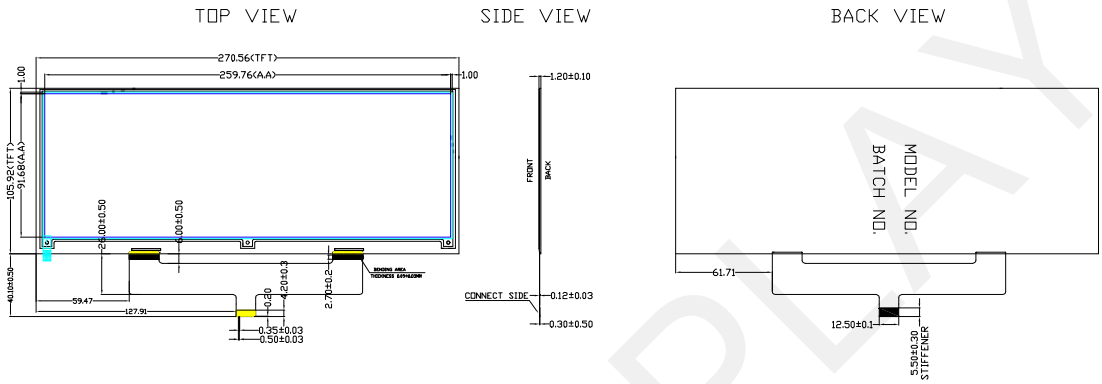
3-4. After 24hour Colour Changed:



W: Max Δ E(W-W)<2, K: Max Δ E(B-B)<2, R: Max Δ Eab(R-R)<2.

4.Mechanical Drawing of EPD Module

Confirmation:



NOTE

1 DISPLAY MODULE 10.85" ARRAY FOR EPD
2 DRIVER IC:JD79686AB
3 RESOLUTION:1360*480
4 PIXEL SIZE:0.191*0.191mm

RoHS

TOLERANCES UNMARKED ANGLES±5° .X=±0.4mm .XX=±0.20mm .XXX=±0.20mm	TITLE: EPD	PROJECT:		REV.: A	DATE: 20.04.15	CUST. P/N:
	DWN. CC ZHENG	CHK. NN ZHAO	APPR. SY ZHAO	UNIT: mm	3RD ANGLE:	PAGE: 1/1

5. Input/output Pin Assignment

No.	Name	I/O	Description	Remark
1	CSB2	I	Chip select input pin	Note 5-1
2	GDR	O	N-Channel MOSFET Gate Drive Control	
3	RESE	I	Current Sense Input for the Control Loop	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSH2	C	Positive Source driving voltage(Red)	
6	TSCL	O	I2C Interface to digital temperature sensor Clock pin	Note 5-6
7	TSDA	I/O	I2C Interface to digital temperature sensor Data pin	Note 5-6
8	BS1	I	Bus Interface selection pin	Note 5-5
9	BUSY	O	Busy state output pin	Note 5-4
10	RES#	I	Reset signal input. Active Low.	Note 5-3
11	D/C#	I	Data /Command control pin	Note 5-2
12	CS#	I	Chip select input pin	Note 5-1
13	SCL	I	Serial Clock pin (SPI)	
14	SDA	I/O	Serial Data pin (SPI)	
15	VDDIO	P	Power Supply for interface logic pins It should be connected with VCI	
16	VCI	P	Power Supply for the chip	
17	VSS	P	Ground	
18	VDD	C	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS	
19	VPP	P	FOR TEST	Keep Open
20	VSH1	C	Positive Source driving voltage	
21	VGH	C	Power Supply pin for Positive Gate driving voltage and VSH1	
22	VSL	C	Negative Source driving voltage	
23	VGL	C	Power Supply pin for Negative Gate driving voltage VCOM and VSL	
24	VCOM	C	VCOM driving voltage	

I = Input Pin, O =Output Pin, I/O = Bi-directional Pin (Input/output), P = Power Pin, C = Capacitor Pin

Note 5-1: This pin (CS#) is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW.

Note 5-2: This pin is (D/C#) Data/Command control pin connecting to the MCU in 4-wire SPI mode. When the pin is pulled HIGH, the data at SDA will be interpreted as data. When the pin is pulled LOW, the data at SDA will be interpreted as command.

Note 5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 5-4: This pin is Busy state output pin. When Busy is Low, the operation of chip should not be interrupted, command should not be sent. The chip would put Busy pin Low when -Outputting display waveform -Communicating with digital temperature sensor.

Note 5-5: Bus interface selection pin

Note 5-6:This pin connect to the VSS if there is no external temperature sensor

BS1 State	MCU Interface
L	4-lines serial peripheral interface(SPI) - 8 bits SPI
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

6. Electrical Characteristics

6.1 Absolute Maximum Rating

Parameter	Symbol	Rating	Unit
Logic supply voltage	VCI	-0.3 to +6.0	V
Logic Input voltage	VIN	-0.3 to TBD	V
Operating Temp range	TOPR	0 to +40	ºC.
Storage Temp range	TSTG	-25 to+40	ºC.
Optimal Storage Temp	TSTGo	23±3	ºC.
Optimal Storage Humidity	HSTGo	55±10	%RH

Note:

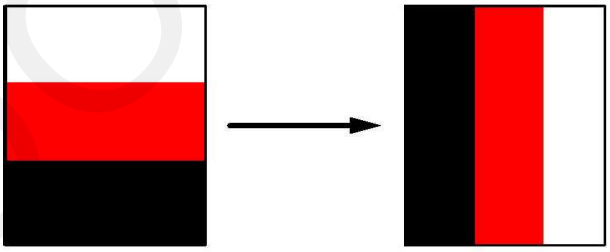
1. **Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Panel DC Characteristics tables.**
2. **We guarantee the single pixel display quality for 0-35℃, but we only guarantee the barcode readable for 35-40℃.**
3. **The storage time is within 10 days for -25℃ ~0℃ or 40℃ ~60℃.**
   The display screen should be kept white and face up.

6.2 Panel DC Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =23ºC.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
Single ground	V_{SS}	-		-	0	-	V
Logic supply voltage	V_{CI}	-	VCI	2.3	3.0	3.6	V
Digital/Analog supply voltage	V_{DD}		VDD	2.3	3.0	3.6	V
High level input voltage	V_{IH}	-	-	0.7 VCI	-	-	V
Low level input voltage	V_{IL}	-	-	GND	-	0.3VDD	V
High level output voltage	V_{OH}	IOH = 400uA	-	VCI -0.4	-	-	V
Low level output voltage	V_{OL}	IOL =- 400uA	-	-	-	GND +0.4	V
Typical power	P_{TYP}	VCI =3.0V	-	-	51	-	mW
Deep sleep mode	P_{STPY}	VCI =3.0V	-	-	0.006	-	mW
Typical operating current	Iopr_VCI	VCI =3.0V	-	-	17	-	mA
Image update time	-	23 ºC	-	-	20	-	sec
Typical peak current	Iopr_VCI	2.3~3.6V			140	280	mA
Sleep mode current	Islp_V_{CI}	DC/DC off No clock No input load Ram data retain	-	-	40	-	uA
Deep sleep mode current	Idslp_V_{CI}	DC/DC off No clock No input load Ram data not retain	-	-	2	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 3 scale pattern to vertical 3 scale pattern.



2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.

3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by Good Display

4. Electrical measurement: Tektronix oscilloscope - MDO3024,

Tektronix current probe - TCP0030A.

6.3 Panel AC Characteristics

6.3.1 MCU Interface Selection

The pin assignment at different interface mode is summarized in Table 6-3-1. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

Pin Name	Data/Command Interface		Control Signal		
Bus interface	SDA	SCL	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDA	SCL	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDA	SCL	CS#	L	RES#

Table 6-3-1: MCU interface assignment under different bus interface mode

6.3.2 MCU Serial Interface (4-wire SPI)

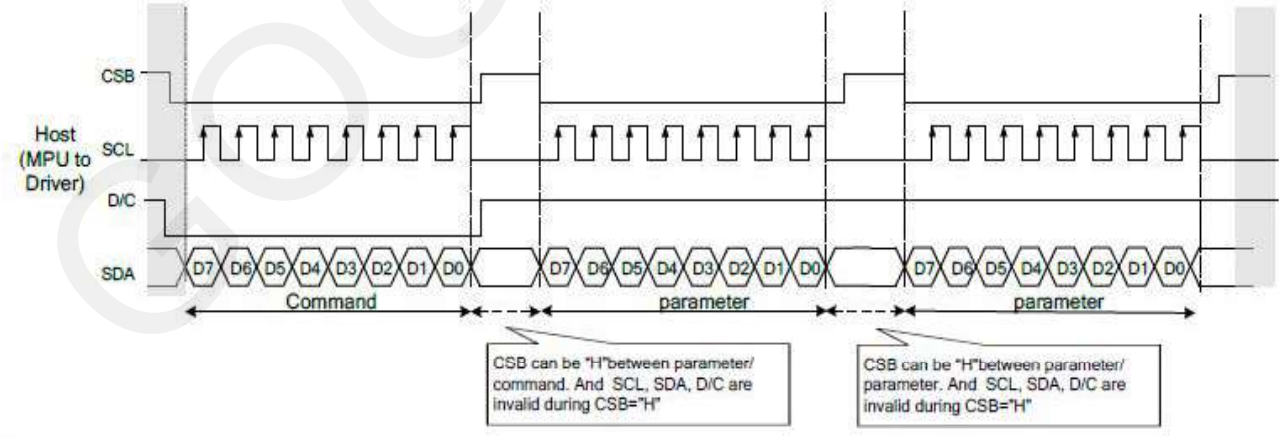
The serial interface consists of serial clock SCL, serial data SDA D/C# CS#. This interface supports Write mode and Read mode.

Function	CS#	D/C#	SCL
Write command	L	L	↑
Write data	L	H	↑

Table 6-3-2: Control ins of 4-wire Serial Peri heral interface

Note: ↑ stands for rising edge of signal

Figure 6-3-1: 4-wire SPI mode



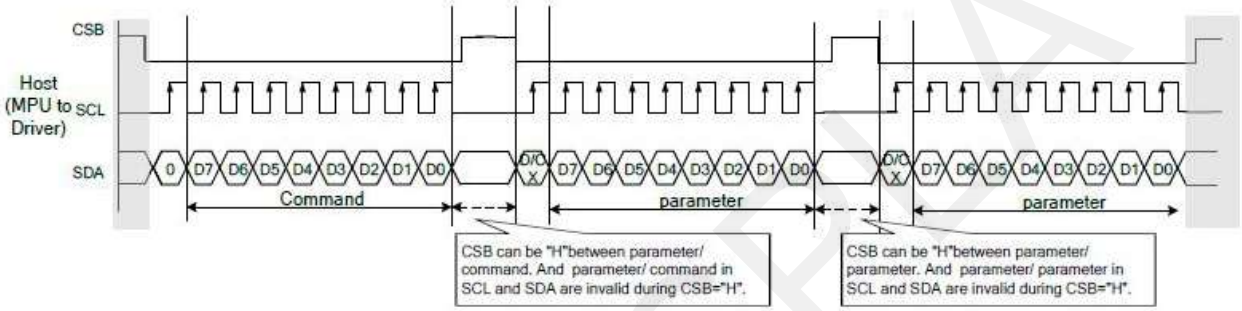
6.3.3 MCU Serial Interface (3-wire SPI)

Function	CS#	D/C#	SCL
Write command	L	Tie	↑
Write data	L	Tie	↑

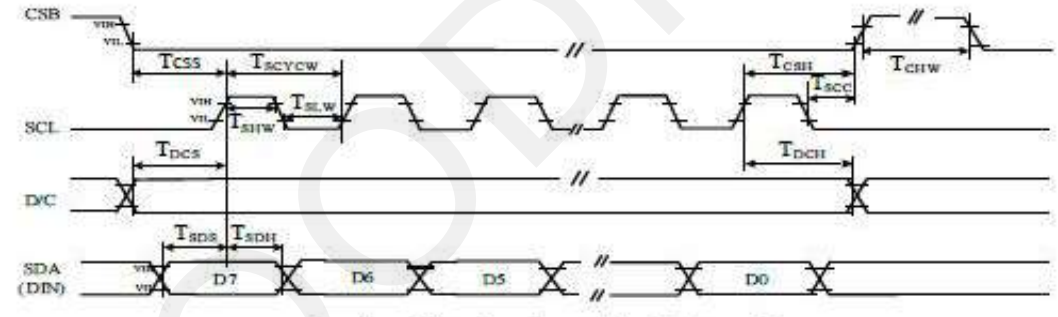
Table 6-3-3: Control pins of 4-wire Serial Peripheral interface

Note：↑ stands for rising edge of signal

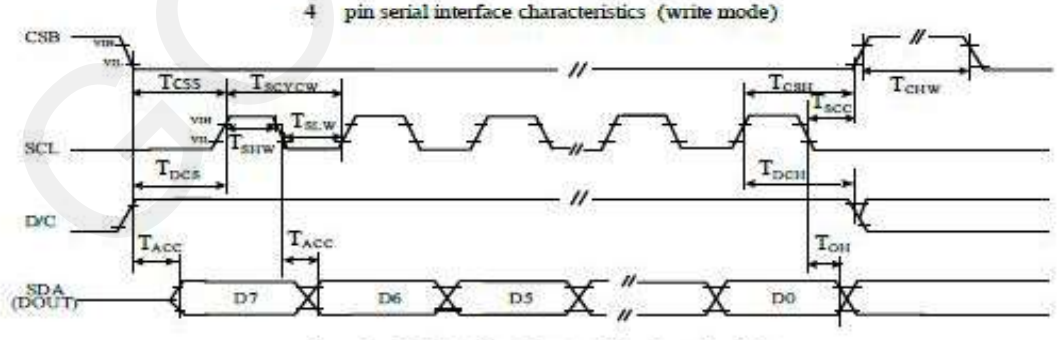
Figure 6-3-2: 3-wire SPI mode



6.3.4 Interface Timing



4 pin serial interface characteristics (write mode)



4 pin serial interface characteristics (read mode)

Serial Interface Timing Characteristics

Symbol	Signal	Parameter	Min	Typ	Max	Unit
Tcss	CS#	Chip Select Setup Time	100	-	-	ns
Tcsh		Chip Select Hold Time	100	-	-	ns
Tscc		Chip Select Setup Time	50	-	-	ns
Tchw		Chip Select Setup Time	500	-	-	ns
Tscycw	SCLK	Serial clock cycle (write)	100	-	-	ns
Tshw		SCL “H” pulse width (write)	35	-	-	ns
Tslw		SCL“L” pulse width (write)	35	-	-	ns
Tscycr		Serial clock cycle (Read)	200	-	-	ns
Tshr		SCL “H” pulse width (Read)	85	-	-	ns
Tslr		SCL “L” pulse width (Read)	85	-	-	ns
Tsds	SDIN (DIN) (DOUT)	Data setup time	30	-	-	ns
Tsdh		Data hold time	30	-	-	ns
Tacc		Access time	10	-	-	ns
Toh		Output disable time	15	-	-	ns

7.Command Table

#	Command	W/R	C/D	D7	D6	D5	D4	D3	D2	D1	D0	Default
1	Panel Setting (PSR)	W	0	0	0	0	0	0	0	0	0	00h
		W	1	RES[1]	RES[0]	REG-EN	BWR	UD	SHL	SHD-N	RST-N	8Fh
2	Power Setting (PWR)	W	0	0	0	0	0	0	0	0	1	01H
		W	1	-	-	-	-	-	-	VDS_EN	VDG_EN	03h
		W	1			-	-	VCOM_HV	VGHL_LV [2]	VGHL_LV [1]	VGHL_LV [0]	00h
		W	1			VSH [5]	VSH [4]	VSH [3]	VSH [2]	VSH [1]	VSH [0]	3Fh
		W	1			VSL [5]	VSL [4]	VSL [3]	VSL [2]	VSL [1]	VSL [0]	3bh
		W	1		VSHR [6]	VSHR [5]	VSHR [4]	VSHR [3]	VSHR [2]	VSHR [1]	VSHR [0]	0Fh
3	Power OFF (POF)	W	0	0	0	0	0	0	0	1	0	02H
4	Power OFF Sequence Setting(PFS)	W	0	0	0	0	0	0	0	1	1	03H
		W	1	-	-	T_VDS_OFF[1]	T_VDS_OFF[0]					00h
5	Power ON (PON)	W	0	0	0	0	0	0	1	0	0	04H
6	Power ON Measure Command	W	0	0	0	0	0	0	1	0	1	05H
7	Booster Soft Start (BTST)	W	0	0	0	0	0	0	1	1	0	06H
		W	1	BT_PHA7	BT_PHA6	BT_PHA5	BT_PHA4	BT_PHA3	BT_PHA2	BT_PHA1	BT_PHA0	17h
		W	1	BT_PHB7	BT_PHB6	BT_PHB5	BT_PHB4	BT_PHB3	BT_PHB2	BT_PHB1	BT_PHB0	17h
		W	1	-	-	BT_PHC5	BT_PHC4	BT_PHC3	BT_PHC2	BT_PHC1	BT_PHC0	17h
8	Deep Sleep(DSLP)	W	0	0	0	0	0	0	1	1	1	07H
		W	1	1	0	1	0	0	1	0	1	A5h
9	Data Start Transmission 1 (DTM1)	W	0	0	0	0	1	0	0	0	0	10H
		W	1	#	#	#	#	#	#	#	#	00H
10	Data Stop (DSP)	W	0	0	0	0	1	0	0	0	1	11H
		R	1	Data_flag	-	-	-	-	-	-	-	--
11	Display Refresh (DRF)	0	0	0	0	0	1	0	0	1	0	12h
12	Data Start transmission 2(DTM2)	W	0	0	0	0	1	0	0	1	1	13H
		W	1	#	#	#	#	#	#	#	#	00h
13	Partial Data Start transmission1 (PDTM1)	W	0	0	0	0	1	0	1	0	0	14H
		W	1	#	#	#	#	#	#	#	#	00h
14	Partial Data Start transmission 2 (PDTM2)	W	0	0	0	0	1	0	1	0	1	15H
		W	1	#	#	#	#	#	#	#	#	00h
15	Partial Display Refresh(PDRF)	W	0	0	0	0	1	0	1	1	0	16H
		W	1	#	#	#	#	#	#	#	#	00h
16	LUT for VCOM (LUT1)	W	0	0	0	1	0	0	0	0	0	20H
		W	1	#	#	#	#	#	#	#	#	00h
17	White to White LUT (LUTWW)	W	0	0	0	1	0	0	0	0	1	21H
		W	1	#	#	#	#	#	#	#	#	00h
18	Black to White LUT	W	0	0	0	1	0	0	0	1	0	22H

	(LUTBW/LUTR)	W	1	#	#	#	#	#	#	#	#	00h
19	White to Black LUT (LUTWB/LUTW)	W	0	0	0	1	0	0	0	1	1	23H
		W	1	#	#	#	#	#	#	#	#	00h
20	Black to Black LUT (LUTBB/LUTB)	W	0	0	0	1	0	0	1	0	0	24H
		W	1	#	#	#	#	#	#	#	#	00h
21	LUTC option	W	0	0	0	1	0	0	1	0	1	25H
		W	1							XON [9:8]		00h
		W	1	XON [7:0]								00h
		W	1							ST_CHV [9:8]		00h
		W	1	ST_CHV [7:0]								00h
22	Set Vcom/Red states	W	0	0	0	1	0	0	1	1	0	26H
		W	1	0	0			vcom_stg_sel[1:0]		b2w_stg_sel[1:0]		00h
23	OSC control (OSC)	W	0	0	0	1	1	0	0	0	0	30H
		W	1			M[2:0]			N[2:0]			3Ah
24	Temperature Sensor Command (TSC)	W	0	0	1	0	0	0	0	0	0	40H
		R	1	D10/TS [7]	D9/TS[6]	D8/TS[5]	D7/TS[4]	D6/TS[3]	D5/TS[2]	D4/TS[1]	D3/TS[0]	--
		R	1	D2	D1	D0	-	-	-	-	-	--
25	Temperature Sensor Calibration(TSE)	W	0	0	1	0	0	0	0	0	1	41H
		W	1	TSE	-	-	-	TO[3]	TO[2]	TO[1]	TO0]	00h
26	Temperature Sensor Write (TSW)	W	0	0	1	0	0	0	0	1	0	42H
		W	1	WATTR [7]	WATTR [6]	WATTR [5]	WATTR [4]	WATTR [3]	WATTR [2]	WATTR [1]	WATTR [0]	00h
		W	1	WMSB [7]	WMSB [6]	WMSB [5]	WMSB [4]	WMSB [3]	WMSB [2]	WMSB [1]	WMSB [0]	00h
		W	1	WLSB[7]	WLSB[6]	WLSB[5]	WLSB[4]	WLSB[3]	WLSB[2]	WLSB[1]	WLSB[0]	00h
27	Temperature Sensor Read (TSR)	W	0	0	1	0	0	0	0	1	1	43H
		R	1	RMSB[7]	RMSB[6]	RMSB[5]	RMSB[4]	RMSB[3]	RMSB[2]	RMSB[1]	RMSB[0]	-
		R	1	RLSB[7]	RLSB[6]	RLSB[5]	RLSB[4]	RLSB[3]	RLSB[2]	RLSB[1]	RLSB[0]	-
28	Vcom and data interval setting(CDI)	W	0	0	1	0	1	0	0	0	0	50H
		W	1	VBD[1]	VBD[0]	DDX[1]	DDX[0]	CDI[3]	CDI[2]	CDI[1]	CDI[0]	D7h
29	Lower Power Detection (LPD)	W	0	0	1	0	1	0	0	0	1	51H
		R	1	-	-	-	-	-	-	-	LPD	-
30	TCON setting (TCON)	W	0	0	1	1	0	0	0	0	0	60H
		W	1	S2G[3]	S2G[2]	S2G[1]-	S2G[0]	G2S[3]	G2S[2]	G2S[1]	G2S[0]	22h
31	TCON resolution (TRES)	W	0	0	1	1	0	0	0	0	1	61H
		W	1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	-	-	-	00h
		W	1	-	-	-	-	-	-	-	VRES(8)	00h
		W	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)	00h
32	Source & gate start setting	W	0	0	1	1	0	0	0	1	0	62H
		W	1	S_start (7)	S_start (6)	S_start (5)	S_start (4)	S_start (3)	-	-	-	00h

		W	1				gscan				G_start [8]	00h
		W	1	G_start (7)	G_start (6)	G_start (6)	G_start (4)	G_start (3)	G_start (2)	G_start (1)	G_start (0)	00h
33	Revision (REV)	W	0	0	1	1	1	0	0	0	0	70H
		R	1	REV[7]	REV[6]	REV[5]	REV[4]	REV[3]	REV[2]	REV[1]	REV[0]	-
		R	1	REV[15]	REV[14]	REV[13]	REV[12]	REV[11]	REV10]	REV[09]	REV[08]	-
34	Get Status(FLG)	W	0	0	1	1	1	0	0	0	1	71H
		R	1	-	PTL_flag	I2C_ERR	I^2C_ BUSYN	Data_flag	PON	POF	BUSY_N	-
35	Auto Measurement Vcom (AMV)	W	0	1	0	0	0	0	0	0	0	80 H
		W	1	-	-	AMVT [1]	AMVT [0]	XON	AMVS	AMV	AMVE	10h
36	Read Vcom Value(VV)	W	0	1	0	0	0	0	0	0	1	81H
		R	1	-	-	VV[5]	VV[4]	VV[3]	VV[2]	VV[1]	VV[0]	-
37	VCM_DC Setting (VDCS)	W	0	1	0	0	0	0	0	1	0	82H
		W	1	-	-	VCDS[5]	VCDS [4]	VCDS [3]	VCDS [2]	VCDS [1]	VCDS [0]	1Fh
38	Program Mode (PGM)	W	0	1	0	1	0	0	0	0	0	A0H
		W	1	1	0	1	0	0	1	0	1	A5h
39	Active program(APG)	W	0	1	0	1	0	0	0	0	1	A1H
40	Read OTP Data (ROTP)	W	0	1	0	1	0	0	0	1	0	A2H
		R	1	#	#	#	#	#	#	#	#	-
41	Force Temperature	W	0	1	1	1	0	0	1	0	1	E5H
		W	1	TS_SET [7]	TS_SET [6]	TS_SET [5]	TS_SET [4]	TS_SET [3]	TS_SET [2]	TS_SET [1]	TS_SET [0]	00h
42	LVD voltage Select	W	0	1	1	1	0	0	1	1	0	E6H
		W	1	-	-	-	-	-	-	LVD_SEL[1]	LVD_SEL[0]	11h
43	Panel Break Check	W	0	1	1	1	0	0	1	1	1	E7H
		R	1	-	-	-		-	-	-	PSTA	-
44	Power saving	W	0	1	1	1	0	1	0	0	0	E8H
		W	1	VCOM_ W[3]	VCOM_ W[2]	VCOM_ W[1]	VCOM_ W[0]	SD_W[3]	SD_W[2]	SD_W[1]	SD_W[0]	00h
45	AUTO sequence	W	0	1	1	1	0	1	0	0	1	E9H
		W	1	1	0	1	0	0	1	0	1	00h
46	OTP LUT backup1 program	W	0	1	1	1	0	1	0	1	1	EBH
47	Read OTP LUT backup1	W	0	1	1	1	0	1	1	0	0	ECH
		R	1	#	#	#	#	#	#	#	#	--
48	OTP LUT backup2 program	W	0	1	1	1	0	1	1	0	1	EDH

		R	1	#	#	#	#	#	#	#	#	--
49	Read OTP LUT backup2	W	0	1	1	1	0	1	1	1	0	EEH
50	Checksum Program to OTP	W	0	1	1	1	0	1	1	1	1	EFH
51	Remap LUT	W	0	1	1	1	1	0	0	0	0	F0H
		W	1	-	-	-	bkup_lut_2_en	rmp2_table_sel[3]	rmp2_table_sel[2]	rmp2_table_sel[1]	rmp2_table_sel[0]	1Fh
		W	1	-	-	-	bkup_lut_1_en	rmp1_table_sel[3]	rmp1_table_sel[2]	rmp1_table_sel[1]	rmp1_table_sel[0]	1Fh
52	Set OTP program	W	0	1	1	1	1	0	0	0	1	F1H
		W	1	-	-	-	-	-	-	LUT_bank	reg_bank	03h
53	Read checksum	W	0	1	1	1	1	0	0	1	0	F2H
		R	1	#	#	#	#	#	#	#	#	00h
54	Calculate Checksum	W	0	1	1	1	1	0	0	1	1	F3H

COMMAND DESCRIPTION

W/R: 0: Write Cycle / 1: Read Cycle C/D: 0: Command / 1: Data D7-D0: –: Don't Care

1）Panel Setting (PSR) (R00H)

R00H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PSR	W	0	0	0	0	0	0	0	0	0
1st Parameter	W	1	RES[1]	RES[0]	REG_EN	BWR	UD	SHL	SHD_N	RST_N

The command defines as :

Bit	Name	Description
0	RST_N	RST_N function 1 : no effect. (default) 0: Booster OFF, Register data are set to their default values, and SEG/BG/VCOM:floating
1	SHD_N	SHD_N function 0 : Booster OFF, register data are kept, and SEG/BG/VCOM are kept floating. 1 : Booster on. **(default)**
2	SHL	SHL function 0: Shift left; First data=Sn →Sn-1 → …→S2 →Last data=S1. 1: Shift right: First data=S1→ S2 → …→Sn-1 → Last data=Sn. **(default)**
3	UD	UD function 0:Scan down; First line=Gn→Gn-1 →…→ G2 → Last line=G1. 1:Scan up; First line=G1 →G2 →…→Gn-1 →Last line=Gn. **(default)**
4	BWR	Color selection setting 0: Pixel with B/W/Red. Run both LU1 and LU2. **(default)** 1: Pixel with B/W. Run LU1 only
5	REG_EN	LUT selection setting 0 : Using LUT from OTP**(default)** 1 : Using LUT from register
7-6	RES[1,0]	Resolution setting 00: Display resolution is 600x448 01: Display resolution is 640x480 10: Display resolution is 720x540 11: Display resolution is 800x600 (default)

Notes:

1. When SHD_N become low, DCDC will turn off. Register and SRAM data will keep until VDD turn off. SD output and VCOM will base on previous condition and keep floating.
2. When RST_N become low, driver will reset. All register will reset to default value. All of the driver's functions will disable. SD output and VCOM will base on previous condition and keep floating.

2) Power setting Register (PWR) (R01H)

R01H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PWR	W	0	0	0	0	0	0	0	0	1
1st Parameter	W	1	-	-	-	-	-	-	VDS_EN	VDG_EN
2nd Parameter	W	1	-	-	-	-	VCOM_HV	VGHL_LV [2]	VGHL_LV [1]	VGHL_LV [0]
3rd Parameter	W	1	-	-	VSH [5]	VSH [4]	VSH [3]	VSH [2]	VSH [1]	VSH [0]
4th Parameter	W	1	-	-	VSL [5]	VSL [4]	VSL [3]	VSL [2]	VSL [1]	VSL [0]
5th Parameter	W	1	-	VSHR [6]	VSHR [5]	VSHR [4]	VSHR [3]	VSHR [2]	VSHR [1]	VSHR [0]

The command defines as :

1st Parameter:

Bit	Name	Description
0	VDG_EN	**Gate power selection.** 0 : External VDNS power from VGH/VGL pins. (VDNG_EN open) 1 : Internal DCDC function for generate VGH/VGL. (default)
1	VDS_EN	**Source power selection.** 0 : External source power from VSH/VSL pins. 1 : Internal DC/DC function for generate VSH/VSL. (default)

2nd Parameter:

Bit	Name	Description
2-0	VGHL_LV	**VGHL_LV Voltage Level.** 000: VGH=20 v, VGL=-20v (default) 001: VGH=19 v, VGL=-19v 010: VGH=18 v, VGL=-18v 011: VGH=17 v, VGL=-17v 100: VGH=16 v, VGL=-16v 101: VGH=15 v, VGL=-15v 110: VGH=14 v, VGL=-14v 111: VGH=13 v, VGL=-13v
3	VCOM_HV	**VCOM Voltage Level** 0: VCOMH=VSH+VCOMDC,VCOML=VSL+VCOMDC(default) 1: VCOMH=VGH, VCOML=VGL

3rd Parameter: Internal VSH power selection for B/W LUT. (Default value: 111111b)

Bit	Name	Description
5-0	VSH	**Internal VSH power selection.** 000000: 2.4 v 000001: 2.6 v 000010: 2.8 v 000011: 3.0 v .... 010111: 7.0V 011000: 7.2 V 011001: 7.4 V .... 111010: 14.0V 111011: 14.2 V 111100: 14.4V 111101: 14.6V 111110: 14.8V 111111: 15.0V

4th Parameter: Internal VSL power selection for B/W LUT. (Default value: 111111b)

Bit	Name	Description
5-0	VSL	Internal VSL power selection. 000000: -2.4 v 000001: -2.6 v 000010: -2.8 v 000011: -3.0 v .... 010111: -7.0V 011000: -7.2 V 011001: -7.4 V .... 111010 :-14.0V 111011: -14.2 V 111100: -14.4 V 111101: -14.6V 111110: -14.8V 111111: -15.0V

5th Parameter: Internal VSHR power selection for Red LUT. (Default value: 00001111b)

Bit	Name	Description
6-0	VSHR	Internal VSL power selection. 0000000: 2.4 v 0000001: 2.5 v 0000010: 2.6 v 0000011: 2.7 v .... 0101110: 7.0 V 0101111: 7.1 V 0110000: 7.2 V .... 1010001: 10.5V 1010010: 10.6 V 1010011: 10.7 V 1010100: 10.8V 1010101: 10.9V 1010110: 11.0V

Notes: VSH>VSHR

3) Power OFF Command (POF)(R02H)

R02H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
POF	W	0	0	0	0	0	0	0	1	0

The command defines as :

After power off command, driver will power off base on power off sequence.

After power off command, BUSY_N signal will drop from high to low. When finish the power off sequence, BUSY_N signal will rise from low to high.

Power off command will turn off charge pump, T-con, source driver, gate driver, VCOM, temperature sensor, but register and SRAM data will keep until VDD off.

SD output and VCOM will keep floating.

4) Power off Sequence Setting Register (PFS)(R03H)

R03H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PFS	W	0	0	0	0	0	0	0	1	1
1st Parameter	W	1	-	-	Vsh_off[1]	Vsh_off [0]	Vsl_off[1]	vsl_off[0]	vshr_off[1]	vshr_off[0]

The command defines as :

Bit	Name	Description
1-0	vshr_off	00: 5ms. (default) 01: 10ms 10: 20ms 11: 40ms
3-2	vsl_off	00: 5ms. (default) 01: 10ms 10: 20ms 11: 40ms
5-4	vsh_off	00: 5ms. (default) 01: 10ms 10: 20ms 11: 40ms

5) Power ON Command (PON)(R04H)

R04H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PON	W	0	0	0	0	0	0	1	0	0

The command defines as :
After power on command, driver will power on base on power on sequence.
After power on command, BUSY_N signal will drop from high to low. When finishing the power o sequence, BUSY_N signal will rise from low to high.

6) Power ON Measure Command(PMES)(R05H)

R05H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PMES	W	0	0	0	0	0	0	1	0	1

The command defines as :
If user wants to read temperature sensor or detect low power in power off mode, user has to send this command.
After power on measure command, driver will switch on relevant commend with Low Power detection (R51H) and temperature measurement. (R40H).

7) Booster Soft Start Command(BTST)(R06H)

R01H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PWR	W	0	0	0	0	0	0	1	1	0
1st Parameter	W	1	BT_PHA7	BT_PHA6	BT_PHA5	BT_PHA4	BT_PHA3	BT_PHA2	BT_PHA1	BT_PHA0
2nd Parameter	W	1	BT_PHB7	BT_PHB6	BT_PHB5	BT_PHB4	BT_PHB3	BT_PHB2	BT_PHB1	BT_PHB0
3rd Parameter	W	1	-	-	BT_PHC5	BT_PHC4	BT_PHC3	BT_PHC2	BT_PHC1	BT_PHC0

The command define as follows:

1st Parameter:

Bit	Name	Description
2-0	Driving strength of phase A	000: period1 001: period2 010: period3 011: period4 100: period5 101: period6 110: period7 111: period8
5-3		000: Strength 1 001: Strength 2 010: Strength 3 (default) 011: Strength 4 100: Strength 5 101: Strength 6 110: Strength 7 111: Strength 8
7-6	Soft start period of phase A	00: 10mS (default) 01: 20mS 10: 30mS 11: 40mS

2nd Parameter:

Bit	Name	Description
2-0	Driving strength of phase B	000: period1 001: period2 010: period3 011: period4 100: period5 101: period6 110: period7 111: period8
5-3		000: Strength 1 001: Strength 2 010: Strength 3 (default) 011: Strength 4 100: Strength 5 101: Strength 6 110: Strength 7 111: Strength 8
7-6	Soft start period of phase B	00: 10mS (default) 01: 20mS 10: 30mS 11: 40mS

3rd Parameter:

Bit	Name	Description
2-0	Minimum OFF time setting of GDR in phase C	000: period1 001: period2 010: period3 011: period4 100: period5 101: period6 110: period7 111: period8
5-3	Driving strength of phase C	000: Strength 1 001: Strength 2 010: Strength 3 (default) 011: Strength 4 100: Strength 5 101: Strength 6 110: Strength 7 111: Strength 8

8) Deep Sleep (DSLP)(R07H)

R07H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
DSLP	W	0	0	0	0	0	0	1	1	1
1st Parameter	W	1	1	0	1	0	0	1	0	1

The command define as follows:

After this command is transmitted, the chip would enter the deep-sleep mode to save power.

The deep sleep mode would return to standby by hardware reset.

The only one parameter is a check code, the command would be excited if check code = 0xA5.

9) Data Start transmission 1 Register(DTM1)(R10H)

R10H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
DTM1	W	0	0	0	0	1	0	0	0	0
1st Parameter	W	1	KPixel1	KPixel2	KPixel3	KPixe4	KPixel5	KPixel6	KPixel7	KPixel8
2nd Parameter	W	1								
...	W	1								
Mth Parameter	W	1	KPixel(n-7)	KPixel(n-6)	KPixel(n-5)	KPixel(n-4)	KPixel(n-3)	KPixel(n-2)	KPixel(n-1)	KPixel(n)

The command define as follows:

The register is indicates that user start to transmit data, then write to SRAM. While data transmission complete, user must send command 11H. Then chip will start to send data/VCOM for panel.

In B/W mode, this command writes “OLD” data to SRAM.

In B/W/Red mode, this command writes “B/W” data to SRAM.

10) Display Refresh Command(DRF)(R12H)

R12H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
DRF	W	0	0	0	0	1	0	0	1	0

The command defines as :

While users send this command, driver will refresh display (data/VCOM) base on SRAM data and LUT. After display refresh command, BUSY_N signal will become "0".

11) Data Start transmission 2 Register (DTM2)(R13H)

R13H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
DTM2	W	0	0	0	0	1	0	0	1	1
1st Parameter	W	1	KPixel1	KPixel2	KPixel3	KPixe4	KPixel5	KPixel6	KPixel7	KPixel8
2nd Parameter	W	1								
...	W	1								
Mth Parameter	W	1	KPixel(n-7)	KPixel(n-6)	KPixel(n-5)	KPixel(n-4)	KPixel(n-3)	KPixel(n-2)	KPixel(n-1)	KPixel(n)

The command define as follows:

The register is indicates that user start to transmit data, then write to SRAM. While data transmission com lete, user must send command 11H. Then chip will start to send data/VCOM for panel.

In B/W mode, this command writes "NEW" data to SRAM.

In B/W/Red mode, this command writes "RED" data to SRAM.

12) LUT for VCOM (LUTC)(R20H)

R20H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTC	W	0	0	0	1	0	0	0	0	0
1st Parameter	W	1	1st Level selection [1:0]		2nd Level selection [1:0]		3rd Level selection [1:0]		4th level selection[1:0]	
2nd Parameter	W	1	1st Frame number [7:0]							
3rd Parameter	W	1	2nd Frame number [7:0]							
4thParameter	W	1	3rd Frame number[7:0]							
5thParameter	W	1	4th Frame number[7:0]							
6thParameter	W	1	Repeat numbers[7:0]							
7th~13th Parameter	W	1	2nd state							
…	W	1	3rd ~9th state							
55th ~60h Parameter	W	1	10th state							

The command defines as:

This register is set for VCOM LUT.

This command stores VCOM Look-Up Table with 10 states of data. Each group contains information for one state and is stored with 6 bytes, while the sixth byte indicates how many times that phase will repeat.

If BWR=0 (BWR mode), User could choose 7~10 groups by R26H (SET_STG)

If BWR=1 (BW mode), only 7 groups are used.

define	description
Level selection [1:0]	00: -VCM_DC 01: VSH+VCM_DC. 10: VSL+VCM_DC. 11: Floating.
Frame number [7:0]	00000000 :0 frame 00000001: 1 frame … 11111110: 254 frame 11111111: 255 frame
Repeat numbers [7:0]	00000000 : 0 00000001: 1 … 11111110: 254 11111111: 255

13) White to White LUT Register(LUTWW)(R21H)

R21H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTWW	W	0	0	0	1	0	0	0	0	1
1st Parameter	W	1	1st Level selection [1:0]		2nd Level selection [1:0]		3rd Level selection [1:0]		4th level selection[1:0]	
2nd Parameter	W	1	1st Frame number [7:0]							
3rd Parameter	W	1	2nd Frame number [7:0]							
4thParameter	W	1	3rd Frame number[7:0]							
5thParameter	W	1	4th Frame number[7:0]							
6thParameter	W	1	Repeat numbers[7:0]							
7th~13th Parameter	W	1	2nd state							
…	W	1	3rd ~9th state							
55th ~60h Parameter	W	1	10th state							

The command defines as:

This command stores White-to-White Look-Up Table with 7 groups of data. Each group contains information for one state and is stored with 6 bytes, while the sixth byte indicates how many times that phase will repeat.

define	description
Level selection [1:0]	00: GND 01: VSH 10: VSL 11: VSHR
Frame number [7:0]	00000000 :0 frame 00000001: 1 frame . 11111110: 254 frame 11111111: 255 frame
Repeat numbers [7:0]	00000000 : 0 time 00000001: 1 time . 11111110: 254 times 11111111: 255 times

14) Black to White LUT or Red LUT Register(LUTBW/LUTR) (R22H)

R22H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTBW/LUTR	W	0	0	0	1	0	0	0	1	0
1st Parameter	W	1	1st Level selection [1:0]		2nd Level selection [1:0]		3rd Level selection [1:0]		4th level selection[1:0]	
2nd Parameter	W	1	1st Frame number [7:0]							
3rd Parameter	W	1	2nd Frame number [7:0]							
4thParameter	W	1	3rd Frame number[7:0]							
5thParameter	W	1	4th Frame number[7:0]							
6thParameter	W	1	Repeat numbers[7:0]							
7th~13th Parameter	W	1	2nd state							
…	W	1	3rd ~9th state							
55th ~60h Parameter	W	1	10th state							

The command defines as:

This command stores White-to-White Look-Up Table with 10 groups of data. Each group contains information for one state and is stored with 6 bytes, while the sixth byte indicates how many times that phase will repeat.

define	description
Level selection [1:0]	00: GND 01: VSH 10: VSL 11: VSHR
Frame number [7:0]	00000000 :0 frame 00000001: 1 frame . 11111110: 254 frame 11111111: 255 frame
Repeat numbers [7:0]	00000000 : 0 time 00000001: 1 time . 11111110: 254 times 11111111: 255 times

15) White to Black LUT or White LUT Register(LUTWB/LUTW)(R23H)

R23H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTWB/LUTW	W	0	0	0	1	0	0	0	1	1
1st Parameter	W	1	1st Level selection [1:0]		2nd Level selection [1:0]		3rd Level selection [1:0]		4th level selection[1:0]	
2nd Parameter	W	1	1st Frame number [7:0]							
3rd Parameter	W	1	2nd Frame number [7:0]							
4thParameter	W	1	3rd Frame number[7:0]							
5thParameter	W	1	4th Frame number[7:0]							
6thParameter	W	1	Repeat numbers[7:0]							
7th~13th Parameter	W	1	2nd state							
…	W	1	3rd ~9th state							
55th ~60h Parameter	W	1	10th state							

The command defines as:

This command stores White-to-White Look-Up Table with 7 groups of data. Each group contains information for one state and is stored with 6 bytes, while the sixth byte indicates how many times that hase will re eat.

define	description
Level selection [1:0]	00: GND 01: VSH 10: VSL 11: VSHR
Frame number [7:0]	00000000 :0 frame 00000001: 1 frame . 11111110: 254 frame 11111111: 255 frame
Repeat numbers [7:0]	00000000 : 0 time 00000001: 1 time . 11111110: 254 times 11111111: 255 times

16) Black to Black LUT or Black LUT Register(LUTBB/LUTB)(R24H)

R24H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTBB/LUTB	W	0	0	0	1	0	0	1	0	0
1st Parameter	W	1	1st Level selection [1:0]		2nd Level selection [1:0]		3rd Level selection [1:0]		4th level selection[1:0]	
2nd Parameter	W	1	1st Frame number [7:0]							
3rd Parameter	W	1	2nd Frame number [7:0]							
4thParameter	W	1	3rd Frame number[7:0]							
5thParameter	W	1	4th Frame number[7:0]							
6thParameter	W	1	Repeat numbers[7:0]							
7th~13th Parameter	W	1	2nd state							
…	W	1	3rd ~9th state							

55th ~60h Parameter	W	1	10th state

The command defines as:

This command stores White-to-White Look-Up Table with 7 groups of data. Each group contains information for one state and is stored with 6 bytes, while the sixth byte indicates how many times that phase will repeat.

define	description
Level selection [1:0]	00: GND 01: VSH 10: VSL 11: VSHR
Frame number [7:0]	00000000 :0 frame 00000001: 1 frame . 11111110: 254 frame 11111111: 255 frame
Repeat numbers [7:0]	00000000 : 0 time 00000001: 1 time . 11111110: 254 times 11111111: 255 times

17) LUTC option(LUTC Option)(R25H)

R25H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTC option	W	0	0	0	1	0	0	1	0	1
1st Parameter	W	1							XON [9:8]	
2nd Parameter	W	1	XON [7:0]							
3rd Parameter	W	1							VCOM_H [9:8]	
4thParameter	W	1	VCOM_H [7:0]							

The command defines as:

This register is set for VCOM LUT.

XON[9:0]	All Gate ON 0000000000: No all gate on. 0000000001: State1 gate power on . 1111111111: State1~10 all gate power on
VCOM_H[9:0]	Control VCOM Power as High 0000000000: No VCOM High voltage 0000000001: State1 VCOM High voltage . 1111111111: State1~10 VCOM High voltage

18) Set VCOM/Red States(SET_STG) (R26H)

R26H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
SET_STG	W	0	0	0	1	0	0	1	1	0
1st Parameter	W	1			-	-	vcom_stg_sel[1:0]		b2w_stg_sel[1:0]	

This command is used to set VCOM/Red LUT states

Function of vcom_stg_sel [1:0]/ b2w_stg_sel[1:0] are shown below

Value	Stages
00	7
01	8
10	9
11	10

Default is set as 7 stages.

19) OSC control Register(OSC)(R30H)

R30H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
OSC	W	0	0	0	1	1	0	0	0	0

1st Parameter	W	1	-	-	M[2:0]	N[2:0]

The command defines as:

The command controls the OSC clock frequency. The OSC structure must support the following frame rates:

M	N	Frame rate	M	N	Frame rate	M	N	Frame rate	M	N	Frame rate
1	1	29HZ	3	1	86HZ	5	1	150HZ	7	1	200HZ
	2	14HZ		2	43HZ		2	72HZ		2	100HZ
	3	10HZ		3	29HZ		3	48HZ		3	67HZ
	4	7HZ		4	21HZ		4	36HZ		4	50HZ (default)
	5	6HZ		5	17HZ		5	29HZ		5	40HZ
	6	5HZ		6	14HZ		6	24HZ		6	33HZ
	7	4HZ		7	12HZ		7	20HZ		7	29HZ
2	1	57HZ	4	1	114HZ	6	1	171HZ			
	2	29HZ		2	57HZ		2	86HZ			
	3	19HZ		3	38HZ		3	57HZ			
	4	14HZ		4	29HZ		4	43HZ			
	5	11HZ		5	23HZ		5	34HZ			
	6	10HZ		6	19HZ		6	29HZ			
	7	8HZ		7	16HZ		7	24HZ			

20) Temperature Sensor Command(TSC)(R40H)

R40H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
TSC	W	0	0	1	0	0	0	0	0	0
1st Parameter	R	1	D10/TS[7]	D9/TS[6]	D8/TS[5]	D7/TS[4]	D6/TS[3]	D5/TS[2]	D4/TS[1]	D3/TS[0]
2nd Parameter	R	1	D2	D1	D0	-	-	-	-	-

The command define as follows:

This command indicates the temperature value.

If R41H(TSE) bit7 set to 0, this command reads internal temperature sensor value.

If R41H(TSE) bit7 set to 1, this command reads external (LM75) temperature sensor value

TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)	TS[7:0]/D[10:3]	T (°C)
11100111	-25	00000000	0	00011001	25
11101000	-24	00000001	1	00011010	26
11101001	-23	00000010	2	00011011	27
11101010	-22	00000011	3	00011100	28
11101011	-21	00000100	4	00011101	29
11101100	-20	00000101	5	00011110	30
11101101	-19	00000110	6	00011111	31
11101110	-18	00000111	7	00100000	32
11101111	-17	00001000	8	00100001	33
11110000	-16	00001001	9	00100010	34
11110001	-15	00001010	10	00100011	35
11110010	-14	00001011	11	00100100	36
11110011	-13	00001100	12	00100101	37
11110100	-12	00001101	13	00100110	38
11110101	-11	00001110	14	00100111	39
11110110	-10	00001111	15	00101000	40
11110111	-9	00010000	16	00101001	41
11111000	-8	00010001	17	00101010	42
11111001	-7	00010010	18	00101011	43
11111010	-6	00010011	19	00101100	44
11111011	-5	00010100	20	00101101	45
11111100	-4	00010101	21	00101110	46
11111101	-3	00010110	22	00101111	47
11111110	-2	00010111	23	00110000	48
11111111	-1	00011000	24	00110001	49

This command only actives after R04H(PON) or R05H(PMES)

21) VCOM and DATA interval setting Register(CDI)(R50H)

R50H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
CDI	W	0	0	1	0	1	0	0	0	0
1st Parameter	W	1	VBD[1]	VBD[0]	DDX[1]	DDX[0]	CDI[3]	CDI[2]	CDI[1]]	CDI[0]

The command defines as:

1st Parameter:

CDI[1:0]: This command indicates the interval of VCOM and data output. When setting the vertical back porch, the total blanking will be keep (20hsync).

Bit	
3-0	Vcom and data interval 0000: 17 hsync 0001:16 hsync 0010:15 hsync 0011:14 hsync 0100:13 hsync 0101:12 hsync 0110:11 hsync 0111:10 hsync 1000:9 hsync 1001:8 hsync 1010:7 hsync 1011:6 hsync 1100:5 hsync 1101:4 hsync 1110:3 hsync 1111:2 hsync

VBD[1:0] Border data selection.

B/W/Red mode(BWR=0)

Bit 5-4	Bit7-6	Description
DDX[0]	VBD[1:0]	LUT
0	00	Floating
	01	LUTR
	10	LUTW
	11	LUTB
1 (default)	00	LUTB
	01	LUTW
	10	LUTR
	11 (default)	Floating

B/W mode (BWR=1)

Bit 5-4	Bit7-6	description
DDX[0]	VBD[1:0]	LUT
0	00	Floating
	01	LUTBW (1->0)
	10	LUTWB (0->1)
	11	Floating
1 (default)	00	Floating
	01	LUTWB (1->0)
	10	LUTBW (0->1)
	11	Floating

DDX[1:0]: Data polarity
1. DDX[1] for RED data, DDX[0] for BW data in the B/W/Red mode
2. DDX[0] for B/W mode

B/W/Red mode(BWR=0)

Bit 5-4	Description	
DDX[1:0]	Data (Red/B/W)	LUT
00	00	LUTW
	01	LUTB
	10	LUTR
	11	LUTR
01 (default)	00	LUTB
	01	LUTW
	10	LUTR
	11	LUTR
10	00	LUTR
	01	LUTR
	10	LUTW
	11	LUTB
11	00	LUTR
	01	LUTR
	10	LUTB
	11	LUTW

B/W mode (BWR=1)

Bit 5-4	Description	
DDX[0]	Data (B/W)	LUT
0	00	LUTWW (0->0)
	01	LUTBW(1->0)
	10	LUTWB(0->1)
	11	LUTBB(1->1)
1 (default)	00	LUTBB(0->0)
	01	LUTWB(1->0)
	10	LUTBW(0->1)
	11	LUTWW(1->1)

22) TCON setting(TCON)(R60H)

R60H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
TCON	W	0	0	1	1	0	0	0	0	0
1st Parameter	W	1	-	-	-	-	-	-	-	LPD

The command define Non-overlap period of gate and source as below:

1st Parameter:

Bit	Period
S2G[3:0]/G2S[3:0]	0000: 2 clock(default) 0001: 4 clock 0010: 6 clock 0011:8 clock 0100: 10 clock 0101: 12 clock 0110: 14 clock 0111: 16 clock 1000: 18 clock 1001: 20 clock 1010: 22 clock 1011: 24 clock 1100: 26 clock 1101: 28 clock 1110: 40 clock 1111: 32 clock

23) Resolution setting(TRES)(R61H)

R61H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
TREAS	W	0	0	1	1	0	0	0	0	1
1st Parameter	W	1							HRES(9)	HRES(8)
2nd Parameter	W	1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	-	-	-

3rd Parameter	W	1							VRES(9)	VRES(8)
4thParameter	W	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)

The command define as follows: When using register:
Horizontal display resolution = HRES Vertical display resolution = VRES
Channel disable calculation:
GD : First G active = G0; LAST active GD= first active +VRES[8:0] -1
SD : First active channel: =S0 ; LAST active SD= first active +HRES[7:3]*8-1
EX :128X272
GD: First G active = G0
LAST active GD= 0+272-1= 271; (G271)
SD : First active channel: =S0
LAST active SD=0+16*8-1=127; (S127)

24) Source & gate start setting(TSGS)(R62H)

R62H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
TSGS	W	0	0	1	1	0	0	0	1	0
1st Parameter	W	1							S_Start (9)	S_Start (8)
2nd Parameter	W	1	S_Start (7)	S_Start (6)	S_Start (5)	S_Start (4)	S_Start (3)	-	-	-
3rd Parameter	W	1							G_Start (9)	G_Start (8)
4thParameter	W	1	G_Start (7)	G_Start (6)	G_Start (5)	G_Start (4)	G_Start (3)	G_Start (2)	G_Start (1)	G_Start (0)

The command define as follows:
1.S_Start [8:0] describe which source output line is the first date line
2.G_Start[8:0] describe which gate line is the first scan line
3.gscan :Gate scan select
0: Normal scan
1: Cascade type 2 scan
Restriction: S_Start should be the multiple of 8

Bit	Function
5-0	Vcom value 000000: -0.1V 000001:-0.15V 000010:-0.2V 111000:-2.9V 111001:-2.95V 111010:-3.0V

25) Program Mode(PGM)(RA0H)

RA0H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
PTIN	W	0	1	0	1	0	0	0	0	0
1st Parameter	W	1	1	0	1	0	0	1	0	1

The command define as follows:
After this command is issued, the chip would enter the program mode.
The mode would return to standby by hardware reset.
The only one parameter is a check code, the command would be executed if check code = 0xA5.

26) Active Program(APG)(RA1H)

RA1H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0

APG	W	0	1	0	1	0	0	0	0	1

The command define as follows:
After this command is transmitted, the programming state machine would be activated.

27) **Read OTP Data(ROTP)(RA2H)**

RA2H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
LUTBB/LUTB	W	0	1	0	1	0	0	0	1	0
1st Parameter	W	1	Dummy							
2nd Parameter	W	1	The data of address 0x000 in the OTP							
3rd Parameter	W	1	The data of address 0x001 in the OTP							
4thParameter	W	1	:							
5thParameter	W	1	The data of address (n-1) in the OTP							
6th~ (m-1)th Parameter	W	1	…							
mth Parameter	W	1	The data of address (n) in the OTP							

The command define as follows:
The command is used for reading the content of OTP for checking the data of programmin . The value of n is depending on the amount of programmed data, the max address = 0xFFF.

28) **Remap LUT command(RM_LUT_CMD)(RF0H)**

RF0H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
RM_LUT_CMD	W	0	1	1	1	1	0	0	0	0
1st Parameter	W	1	-	-	-	tr10_lut_en	rmp2_table_sel[3]	rmp2_table_sel[2]	rmp2_table_sel[1]	rmp2_table_sel[0]
2nd Parameter	W	1	-	-	-	tr9_lut_en	Rmp1_table_sel[3]	Rmp1_table_sel[2]	Rmp1_table_sel[1]	Rmp1_table_sel[0]

The command is used for indicating backup OTP blocks to remap for LUTs

Addr (hex)	OTP Bank 0 (3K Bytes)	Addr (hex)	OTP Bank 1 (3K Bytes)
00h~0Fh	Temp. segment	C00h~C0Fh	Temp. segment
20h~60h	Default setting	C20h~C60h	Default setting
100h	TR0 WF	D00h	TR0 WF
200h	TR1 WF	E00h	TR1 WF
300h	TR2 WF	F00h	TR2 WF
400h	TR3 WF	1000h	TR3 WF
500h	TR4 WF	1100h	TR4 WF
600h	TR5 WF	1200h	TR5 WF
700h	TR6 WF	1300h	TR6 WF
800h	TR7 WF	1400h	TR7 WF
900h	TR8 WF	1500h	TR8 WF
A00h	TR9 WF / Backup 1	1600h	TR9 WF / Backup 1
B00h	TR10 WF / Backup 2	1700h	TR10 WF / Backup 2

1st Parameter:
tr10_lut_en :

Value	Function
1	OTP Address B00h~BFFh is used as "TR10 WF"
0	OTP Address B00h~BFFh is used as "Backup 2", And you can replace one of TR0 ~TR9.

rmp2_tab_sel [3:0] :
Only be functional when tr10_lut_en is set "0", target LUTs to be replaced is shown below

Value	Target LUTs
0001	TR0
0010	TR1
0011	TR2
0100	TR3
0101	TR4
0110	TR5
0111	TR6
1000	TR7
1001	TR8
1010	TR9
1011~1111	None

2nd Parameter
tr9_lut_en :

Value	Function
1	OTP Address B00h~BFFh is used as "TR9 WF"
0	OTP Address B00h~BFFh is used as "Backup 1", And you can replace one of TR0 ~TR8.

rmp1_tab_sel[3:0]
Only be functional when tr9_lut_en is set "0", target LUTs to be replaced is shown below

Value	Target LUTs
0001	TR0
0010	TR1
0011	TR2
0100	TR3
0101	TR4
0110	TR5
0111	TR6
1000	TR7
1001	TR8
1010~1111	None

Notice :
If rmp1_tab_sel = rmp2_tab_sel , the control hardware will reload "backup 1" block to replace target LUT.

29) Set OTP program bank(SET_OTP_BANK)(RF1H)

REEH	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
SET_OTP_BANK	W	0	1	1	1	1	0	0	0	1
1st Parameter	W	1			-	-	-	-	LUT_bank0	reg_bank0

This command is used to set program bank for registers and LUTs

Addr (hex)	OTP Bank 0 (3K Bytes)	Addr (hex)	OTP Bank 1 (3K Bytes)
00h~0Fh	Temp. segment	C00h~C0Fh	Temp. segment
20h~60h	Default setting	C20h~C60h	Default setting
100h~BFFh	LUTs	D00h~17FFh	LUTs

reg_bank :

Value	Function
1	Program "Temp. segment" and "Default Setting" in bank 0
0	Program "Temp. segment" and "Default Setting" in bank 1

LUT_bank :

Value	Function
1	Program "LUTs" in bank 0
0	Program "LUTs" in bank 1

30) Read checksum information(RD_CHKSUM)(RF2H)

RF2H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
RD_CHKSUM	W	0	1	1	1	1	0	0	1	0
1st ~9th Parameter	R	1	Checksum from "TR0 WF" to "TR8 WF"							
10th Parameter	R	1	Checksum of "TR9 WF / backup 1"							
11th Parameter	R	1	Checksum of "TR10 WF / backup 2"							
12th Parameter	R	1	Checksum comparison result from "TR0 WF" to "TR7 WF"							
13th Parameter	R	1	Checksum comparison result from "TR8" and "TR10 WF / backup 2"							

This command is to read checksum information from OTP.

1st to 11th Parameter : Checksum from "TR0 WF" to "TR10 WF / backup 2"

12th Parameter

D7	D6	D5	D4	D3	D2	D1	D0
fault_TR7	fault_TR6	fault_TR5	fault_TR4	fault_TR3	fault_TR2	fault_TR1	fault_TR0

13th Parameter

D7	D6	D5	D4	D3	D2	D1	D0
-	-	-	-	-	fault_TR10 / fault_backup2	fault_TR9 / fault_backup1	fault_TR9

definition of fault_TRx / fault_backup_x

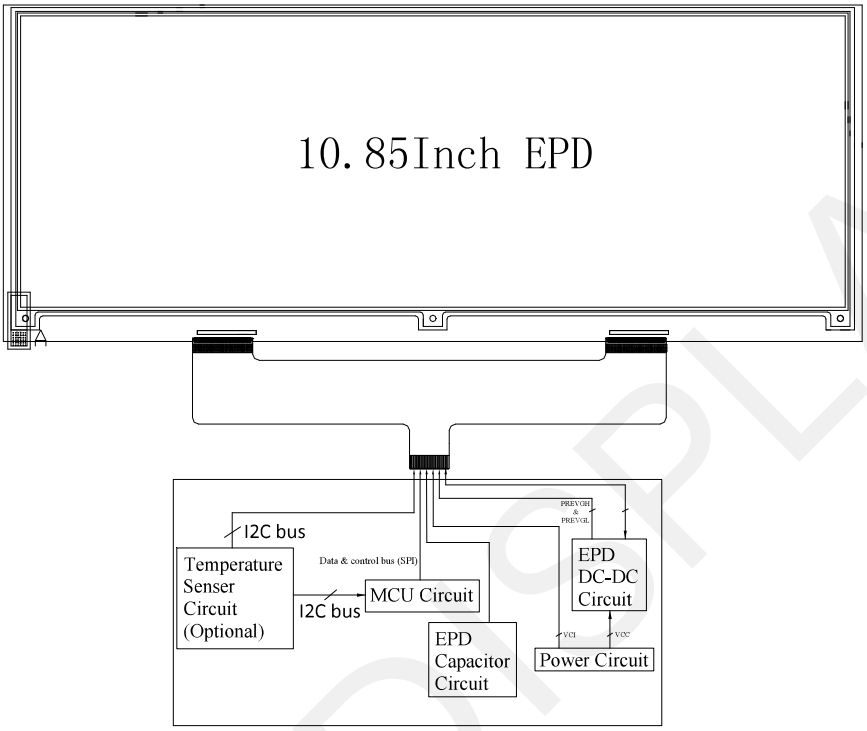
Value	Function
0	Checksum comparison : Equal
1	Checksum comparison : Not Equal

31) RF3H (CAL_CHKSUM): Calculate Checksum

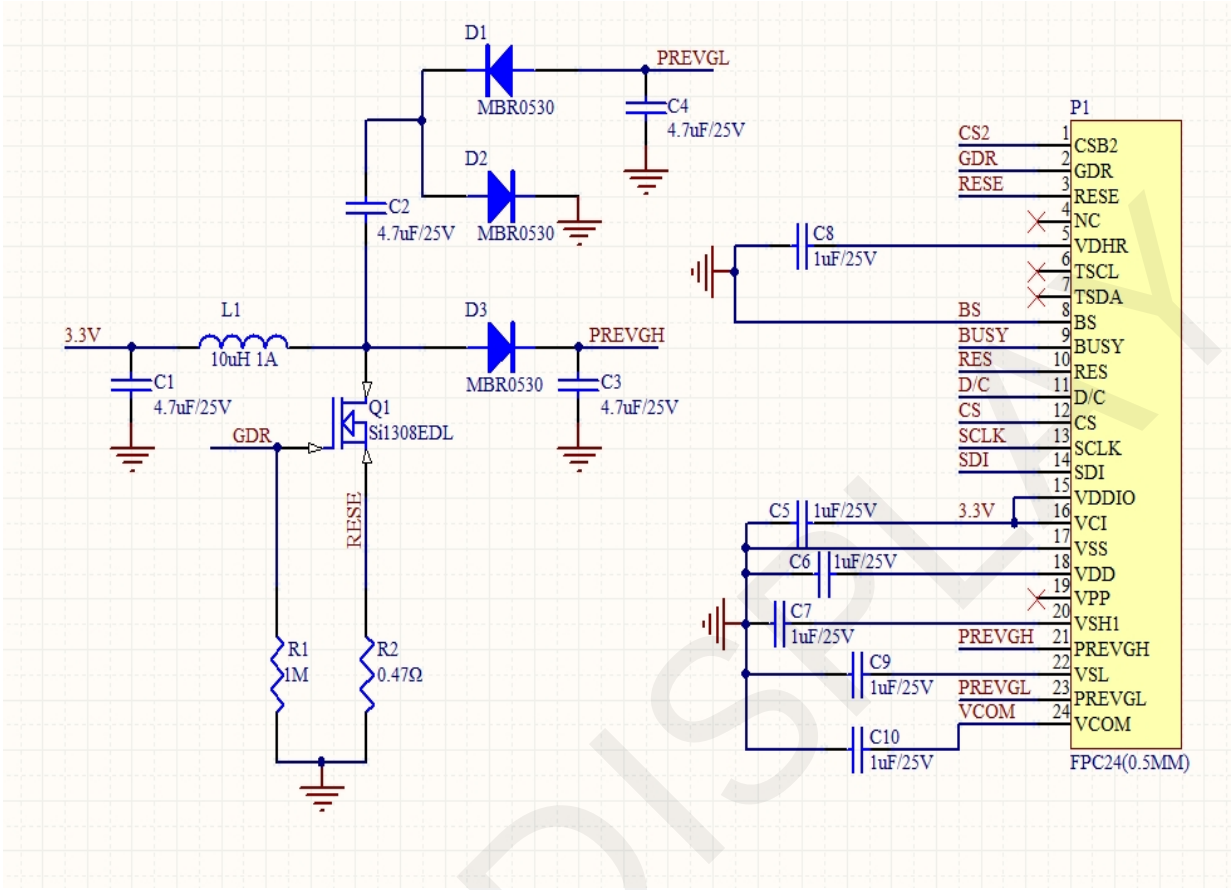
RF3H	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0
CAL_CHKSUM	W	0	1	1	1	1	0	0	1	1

This command is used to Calculate Checksum of LUT Table

8. Block Diagram

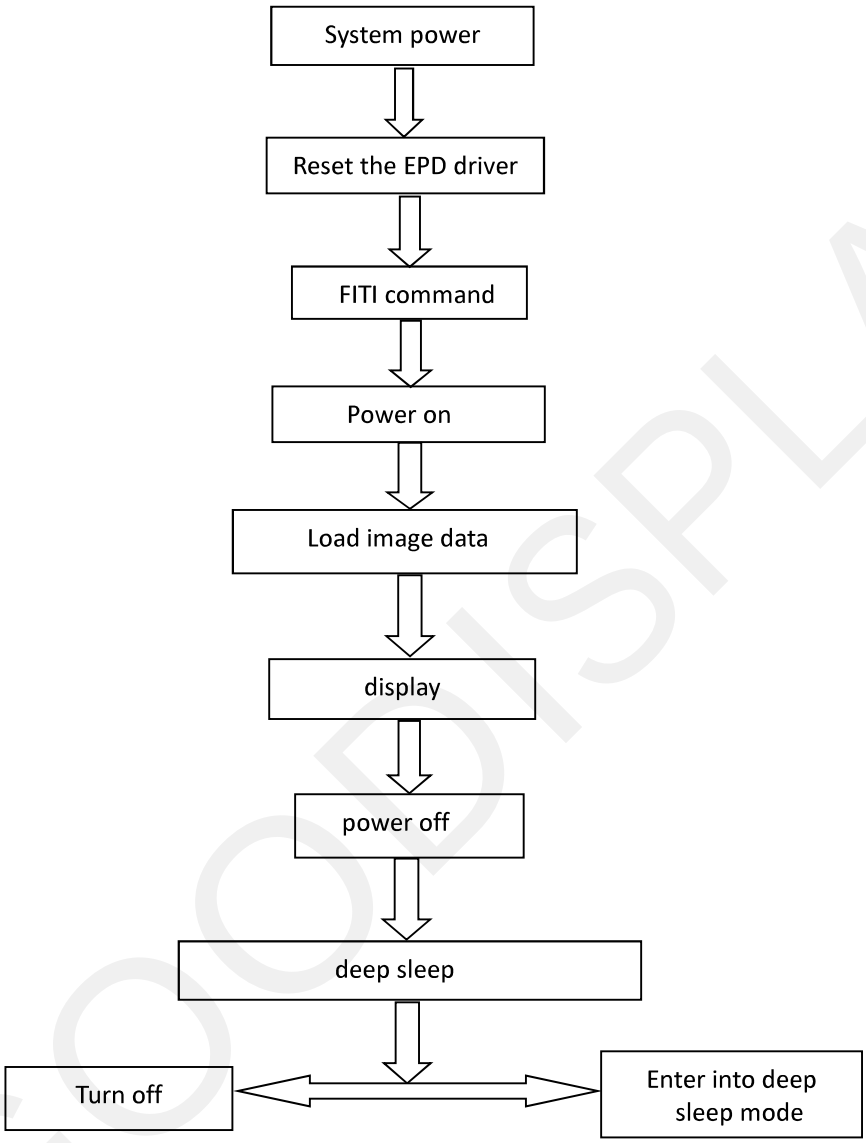


9. Typical Application Circuit with SPI Interface

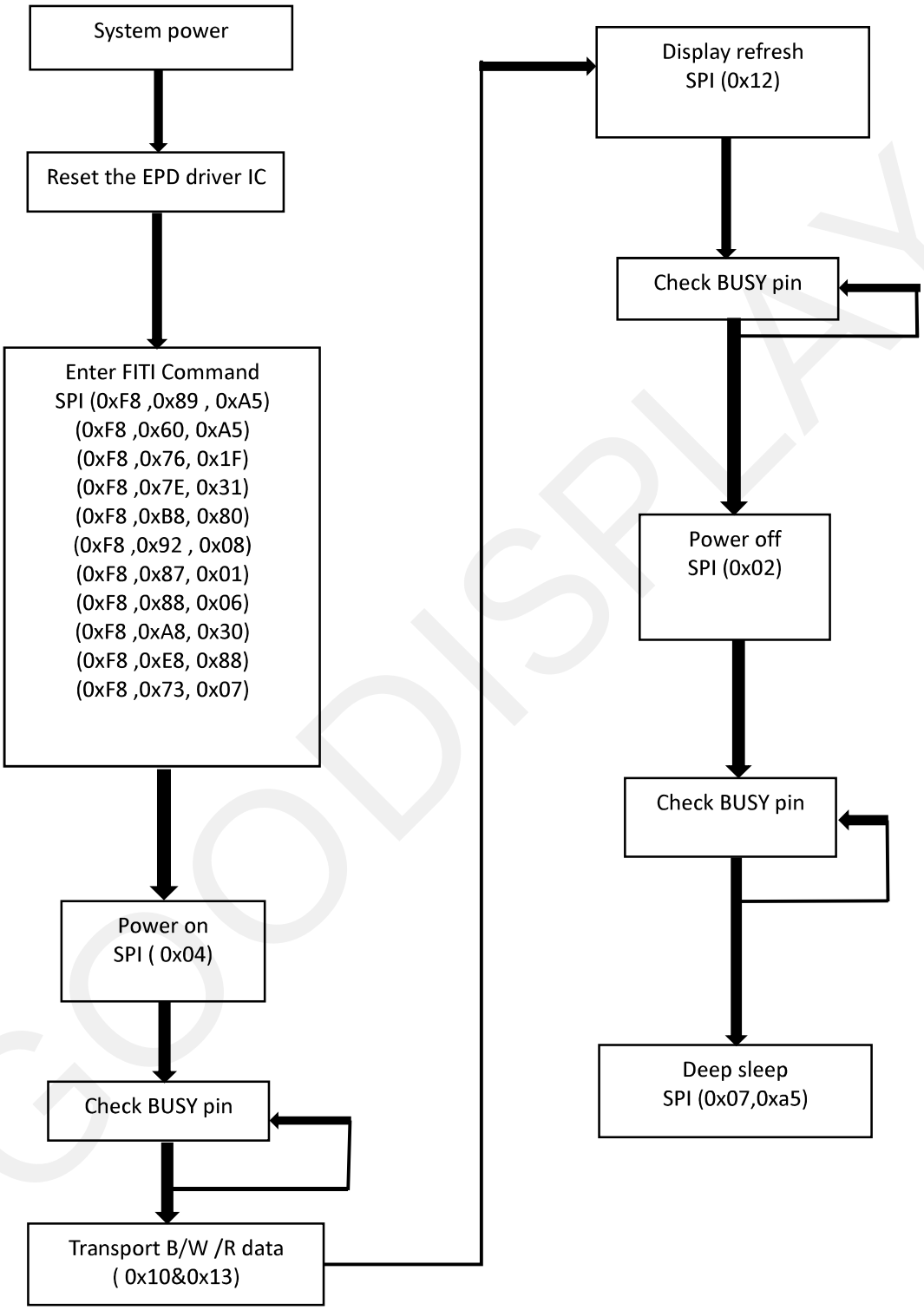


10.Typical Operating Sequence

10.1 OTP Operation Flow



10.2 OTP Operation Reference Program Code



11. Reliability Test

NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 240 h Test in white pattern
2	High-Temperature Storage	T=60℃，RH=40%，240h Test in white pattern
3	High-Temperature Operation	T=40℃，RH=35%，240h
4	Low-Temperature Operation	0℃，240h
5	High-Temperature, High-Humidity Operation	T=40℃，RH=80%，240h
6	High Temperature, High Humidity Storage	T=50℃，RH=80%, 240h Test in white pattern
7	Temperature Cycle	1 cycle:[-25°C 30min]→[+60 °C 30 min] : 50 cycles Test in white pattern
8	ESD Gun	Air+/-4KV;Contact+/-2KV Contact+/-2KV(HBM C:100pF;R:1.5k ohm) Contact+/-200V(MM C:200pF;R:0 ohm) (Naked EPD display,including IC and FPC area)

Note：1. Stay white pattern for storage and non-operation test.
2. Operation is black→white-red pattern, the interval is 150s.
3. Put in 20℃--25℃ for 1hour after test finished, The function ,appearance and display performance is OK.

12. Quality Assurance

12.1 Environment

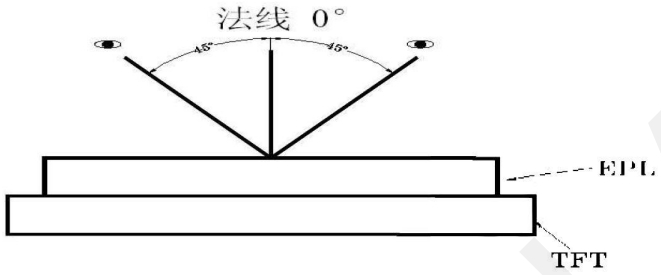
emperature： 25±3℃

Humidity：55±10%RH

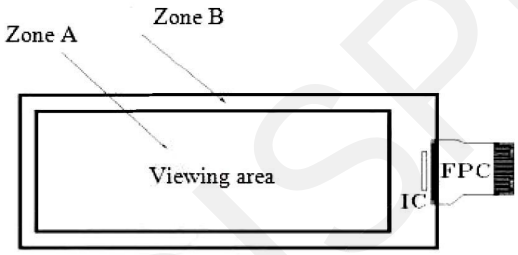
12.2 Illuminance

Brightness:1200～1500LUX;distance: 30CM;Angle:Relate 45°surround.

12.3 Inspect method

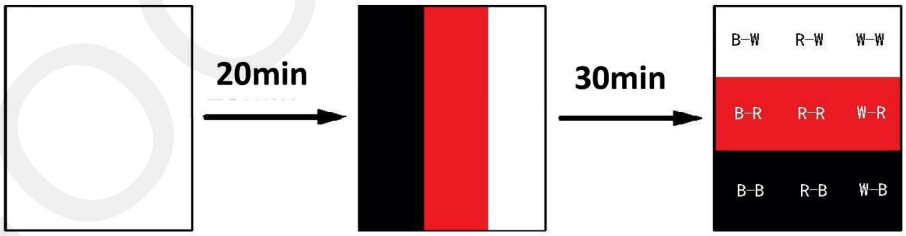


12.4 Display area



12.5 Ghosting test method

Three-color ghosting is measured with following transition from horizontal 3 scale pattern to vertical 3 scale pattern. The listed optical characteristics are only guaranteed under the controller & waveform rovided by Good Display



1）Measurement Instruments：X-rite i1Pro

2）Ghosting formula:

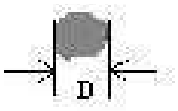
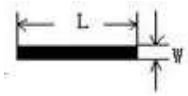
W ghosting：△E= Max (Δ Eab(W-W, R-W), Δ Eab(W-W, B-W), Δ Eab(B-W, R-W))

K ghosting：△E= Max (Δ Eab(B-B, W-B), Δ Eab(B-B, R-B), Δ Eab(R-B, W-B))

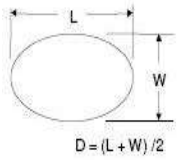
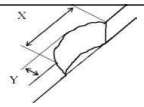
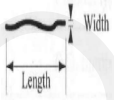
R ghosting：△E= Max (Δ Eab(R-R, W-R), Δ Eab(R-R, B-R), Δ Eab(B-R, W-R))

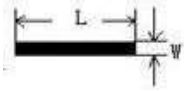
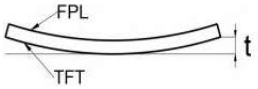
12.6 Inspection standard

12.6.1 Electric inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	Display	Display complete Display uniform	MA	Visual inspection	
2	Black/White spots	 D≤0.4mm， negligible 0.4mm ＜ D≤0.7mm, N≤6 , Allowed 0.7mm＜D Not Allow	MI		
3	Black/White spots (No switch)	 L≤2.0mm,W≤0.2mm negligible 2.0mm＜L≤8.0mm 0.2mm＜W≤0.5mm N≤5 allowable L ＞ 8.0mm ,W ＞ 0.5mm is not allowed		Visual/ Inspection card	Zone A
4	Ghost image	Allowed in switching process	MI	Visual inspection	
5	Flash spots/ Larger FPL size	Flash spots in switching, Allowed FPL size larger than viewing area, Allowed	MI	Visual/ Inspection card	Zone A Zone B
6	Display wrong/Missing	All appointed displays are showed correct	MA	Visual inspection	Zone A
7	Short circuit/ Circuit break/ Display abnormal	Not Allow			

12.6.2 Appearance inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	B/W spots /Bubble/ Foreign bodies/ Dents	 D≤0.4mm，negligible 0.4mm＜D≤0.7mm，N≤6 allowable D＞0.7mm，Not Allow	MI	Visual inspection	Zone A
2	Glass crack	Not Allow	MA	Visual / Microscope	Zone A Zone B
3	\Dirty	Allowed if can be removed	MI		Zone A Zone B
4	Chips/Scratch/ Edge crown	 X≤3mm,Y≤0.5mm And without affecting the electrode is permissible  2mm≤X or 2mm≤Y Not Allow  W≤0.1mm,L≤5mm, No harm to the electrodes and N≤2 allow	MI	Visual / Microscope	Zone A Zone B
5	TFT Cracks	 Not Allow	MA	Visual / Microscope	Zone A Zone B
6	Dirty/ foreign body	Allowed if can be removed/ allow	MI	Visual / Microscope	Zone A / Zone B
7	FPC broken/ FPC oxidation / scratch	  Not Allow	MA	Visual / Microscope	Zone B

8	B/W Line	 L≤2.0mm,W≤0.2mm negligible 2.0mm＜L≤8.0mm 0.2mm＜W≤0.5mm N≤5 allowable L＞8.0mm ,W＞0.5mm is not allowed	MI	Visual / Microscope	Zone A / Zone B
9	TFT edge bulge /TFT chromatic aberration	TFT edge bulge： X≤3mm，Y≤0.3mm Allowed TFT chromatic aberration :Allowed	MI	Visual / Microscope	Zone A Zone B
10	Electrostatic point	D≤0.3mm, allow 0.3mm＜D≤0.5mm ,n≤4 allow D＞0.5mm is not allowed (n≤10 items are allowed within 5 mm in diameter)	MI	Visual / Microscope	Zone A
11	PCB damaged/ Poor welding/ Curl	PCB（Circuit area）damaged Not Allow PCB Poor welding Not Allow PCB Curl≤1%	MI	Visual / Ruler	Zone B
12	Edge glue height/ Edge glue bubble	Edge Adhesives H≤PS surface (Including protect film) Edge adhesives seep in≤1/2 Margin width Length excluding Edge adhesives bubble：bubble Width ≤1/2 Margin width；Length ≤0.5mm。n≤5	MI	Visual Inspection	Zone B
13	Protect film	Surface scratch but not effect protect function, Allow	MI	Visual Inspection	Zone B
14	Silicon glue	Thickness≤PS surface(With protect film): Full cover the IC; Shape: The width on the FPC≤0.5mm (Front) The width on the FPC≤ 1.0mm (Back) smooth surface, No obvious raised.	MI	Visual Inspection	
15	Warp degree (TFT substrate)	 t≤2.0mm	MI	Ruler	
16	Color difference in COM area (Silver point area)	Allowed		Visual Inspection	

13.Packaging

EPD PACKING INSTRUCTION

DATE	2021.07.06
DESIGN	
CHECKED	
APPROVED	

P/N	Customer Code	Ref.P/N

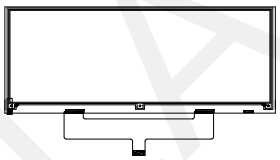
Type	PKG Method	Marking	Surface Marks	Pull Tape	
GLASS	Blister	BACK	None	YES	

Packing Materials List

List	Model	Materials	Q'ty	Unit
Carton	7# 417*362*229 mm	corrugate	1	Piece
Inner Carton	7#(INNER)400*343 *95 mm	corrugate	2	Piece
Blister		PET	22	Piece
Thin foam	304.67*267.17*T1.5~1.8MM	EPE	20	Piece
Antistatic vacuum bag	450*590*0.075		2	Piece
Foam board		EPE	3	Piece
PULL TAPE	16*5*T0.05		40	Piece

2PCS/LAYER, 20LAYER/CTN, TOTAL 40PCS/CTN.

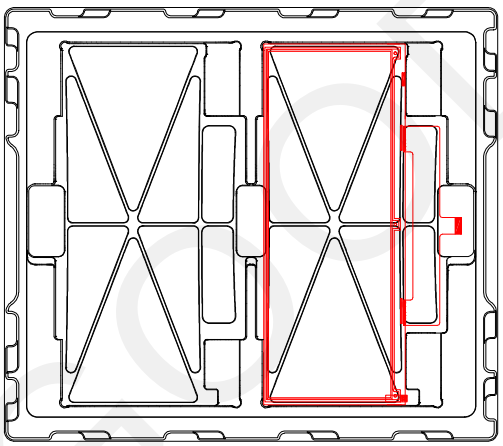
Pull tape:



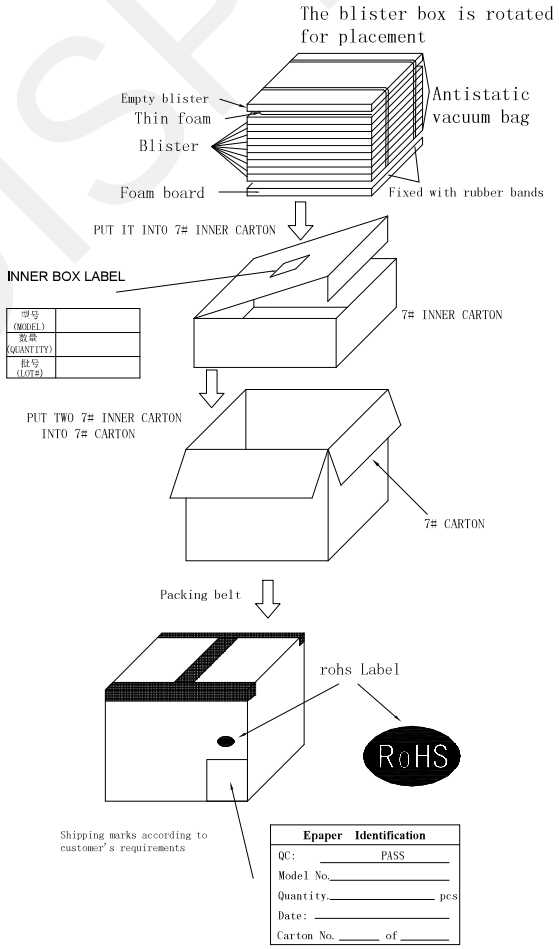
Detail:

Blister box:

Note: there are 20 layers of products, divided into 2 inner boxes, and an empty blister box is placed on the top of each inner box, so the number of blister boxes is 22



QUANTITY: 2PCS



14. Others

14.1 Matched Development Kit

Our Development Kit designed for SPI E-paper Display aims to help users to learn how to use E-paper Display more easily. It can refresh black-white E-paper Display, three-color (black, white and red/Yellow) E-paper Display and four-color(black, white, red and yellow) Good Display 's E-paper Display. And it is also added the functions of USB serial port, FLASH chip, font chip, current detection ect.
Development Kit consists of the development board and the pinboard.

Supported development platforms include STM32, ESP32, ESP8266, Arduino UNO, etc. More details, please click to the following links:

STM32	https://www.good-display.com/product/219.html
ESP32	https://www.good-display.com/product/338.html
ESP8266	https://www.good-display.com/product/220.html
Arduino UNO	https://www.good-display.com/product/222.html

14.2 Handling, Safety and Environmental Requirements

WARNING
The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

CAUTION
The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.
Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status	
Product specification	The data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and dose not form part of the specification.	

Product Environmental certification
RoHS

14.3 Precautions

(1) Do not apply pressure to the EPD panel in order to prevent damaging it.

(2) Do not connect or disconnect the interface connector while the EPD panel is in operation.

(3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.

(4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.

(5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL / EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue

(6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.